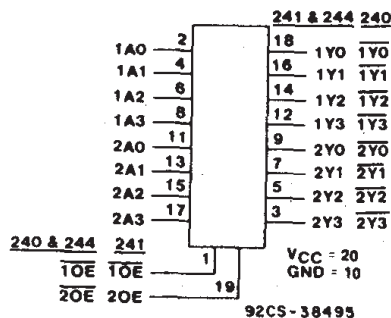




Data sheet acquired from Harris Semiconductor
SCHS287B – Revised January 2004



Octal Buffer/Line Drivers, 3-State

CD54/74AC/ACT240 - Inverting

CD54/74AC/ACT241 - Non-Inverting

CD54/74AC/ACT244 - Non-Inverting

Type Features:

- Buffered inputs
- Typical propagation delay:
3.6 ns @ $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$, $C_L = 50\text{ pF}$

FUNCTIONAL DIAGRAM & TERMINAL ASSIGNMENT

The RCA CD54/74AC240, CD54/74AC241, and CD54/74AC244 and the CD54/74ACT240, CD54/74ACT241, and CD54/74ACT244 3-state octal buffer/line drivers use the RCA ADVANCED CMOS technology. The CD54/74AC/ACT240 and CD54/74AC/ACT244 have active-LOW output enables (1OE, 2OE). The CD54/74AC/ACT241 has one active-LOW (1OE) and one active-HIGH (2OE) output enable.

The CD74AC240 and CD74ACT240 are supplied in 20-lead dual-in-line plastic packages (E suffix) and 20-lead small-outline packages (M and M96 suffixes). The CD74AC241 is supplied in 20-lead dual-in-line plastic packages (E suffix) and the CD74ACT241 is supplied in 20-lead dual-in-line plastic packages (E suffix) and 20-lead small-outline packages (M96 suffix). The CD74AC244 and CD74ACT244 are supplied in 20-lead dual-in-line plastic packages (E suffix), 20-lead small-outline packages (M and M96 suffixes), and 20-lead shrink small-outline packages (SM96 suffix). These package types are operable over the following temperature ranges: Commercial (0 to 70°C); Industrial (-40 to +85°C); and Extended Industrial/Military (-55 to +125°C).

The CD54AC240 and CD54AC244 and the CD54ACT240, CD54ACT241, and CD54ACT244 are supplied in 20-lead hermetic dual-in-line ceramic packages (F3A suffix) and are operable over the -55 to +125°C temperature range.

Family Features:

- Exceeds 2-kV ESD Protection - MIL-STD-883, Method 3015
- SCR-Latch-up-resistant CMOS process and circuit design
- Speed of bipolar FAST[®]/AS/S with significantly reduced power consumption
- Balanced propagation delays
- AC types feature 1.5-V to 5.5-V operation and balanced noise immunity at 30% of the supply
- ± 24 -mA output drive current
 - Fanout to 15 FAST[®] ICs
 - Drives 50-ohm transmission lines

*FAST is a Registered Trademark of Fairchild Semiconductor Corp.

TRUTH TABLES

INPUTS		OUTPUT
$\overline{10E}, \overline{20E}$	A	Y
L	L	H
L	H	L
H	X	Z

(AC/ACT240)

INPUTS		OUTPUT
$\overline{10E}, \overline{20E}$	A	Y
L	L	L
L	H	H
H	X	Z

(AC/ACT244)

INPUTS		OUTPUT	INPUTS		OUTPUT
10E	1A	1Y	20E	2A	2Y
L	L	L	L	X	Z
L	H	H	H	L	L
H	X	Z	H	H	H

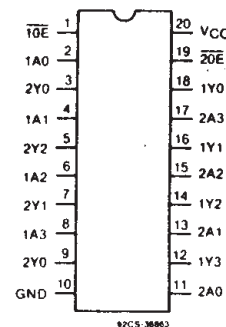
(AC/ACT241)

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
Z = HIGH Impedance

This data sheet is applicable to the CD54/74AC240, CD54ACT240, and CD54/74ACT241. The CD54/74AC241 were not acquired from Harris Semiconductor. See SCHS244 for information on the CD74ACT240, CD74AC244, and CD74ACT244.

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CD54/74AC240/241/244

CD54/74ACT240/241/244

STATIC ELECTRICAL CHARACTERISTICS: AC Series

CHARACTERISTICS	TEST CONDITIONS		V _{cc} (V)	AMBIENT TEMPERATURE (T _A) - °C						UNITS
				+25		-40 to +85		-55 to +125		
	V _I (V)	I _O (mA)		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
High-Level Input Voltage V _{IH}			1.5	1.2	—	1.2	—	1.2	—	V
			3	2.1	—	2.1	—	2.1	—	
			5.5	3.85	—	3.85	—	3.85	—	
Low-Level Input Voltage V _{IL}			1.5	—	0.3	—	0.3	—	0.3	V
			3	—	0.9	—	0.9	—	0.9	
			5.5	—	1.65	—	1.65	—	1.65	
High-Level Output Voltage V _{OH}	V _{IH} or V _{IL}	-0.05	1.5	1.4	—	1.4	—	1.4	—	V
		-0.05	3	2.9	—	2.9	—	2.9	—	
		-0.05	4.5	4.4	—	4.4	—	4.4	—	
		-4	3	2.58	—	2.48	—	2.4	—	
		-24	4.5	3.94	—	3.8	—	3.7	—	
	#, *	-75	5.5	—	—	3.85	—	—	—	
		-50	5.5	—	—	—	—	3.85	—	
Low-Level Output Voltage V _{OL}	V _{IH} or V _{IL}	0.05	1.5	—	0.1	—	0.1	—	0.1	V
		0.05	3	—	0.1	—	0.1	—	0.1	
		0.05	4.5	—	0.1	—	0.1	—	0.1	
		12	3	—	0.36	—	0.44	—	0.5	
		24	4.5	—	0.36	—	0.44	—	0.5	
	#, *	75	5.5	—	—	—	1.65	—	—	
		50	5.5	—	—	—	—	—	1.65	
Input Leakage Current I _I	V _{cc} or GND		5.5	—	±0.1	—	±1	—	±1	μA
3-State Leakage Current I _{OZ}	V _{IH} or V _{IL} V _O = V _{cc} or GND		5.5	—	±0.5	—	±5	—	±10	μA
Quiescent Supply Current, MSI I _{cc}	V _{cc} or GND	0	5.5	—	8	—	80	—	160	μA

#Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.

*Test verifies a minimum 50-ohm transmission-line-drive capability at +85°C, 75 ohms at +125°C.

CD54/74AC240/241/244

CD54/74ACT240/241/244

STATIC ELECTRICAL CHARACTERISTICS: ACT Series

CHARACTERISTICS	TEST CONDITIONS		V _{CC} (V)	AMBIENT TEMPERATURE (T _A) - °C						UNITS
				+25		-40 to +85		-55 to +125		
	V _i (V)	I _o (mA)		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
High-Level Input Voltage V _{IH}			4.5 to 5.5	2	—	2	—	2	—	V
Low-Level Input Voltage V _{IL}			4.5 to 5.5	—	0.8	—	0.8	—	0.8	V
High-Level Output Voltage V _{OH}	V _{IH} or V _{IL} #, * {	-0.05	4.5	4.4	—	4.4	—	4.4	—	V
		-24	4.5	3.94	—	3.8	—	3.7	—	
		-75	5.5	—	—	3.85	—	—	—	
		-50	5.5	—	—	—	—	3.85	—	
Low-Level Output Voltage V _{OL}	V _{IH} or V _{IL} #, * {	0.05	4.5	—	0.1	—	0.1	—	0.1	V
		24	4.5	—	0.36	—	0.44	—	0.5	
		75	5.5	—	—	—	1.65	—	—	
		50	5.5	—	—	—	—	—	1.65	
Input Leakage Current I _I	V _{CC} or GND		5.5	—	±0.1	—	±1	—	±1	μA
3-State Leakage Current I _{OZ}	V _{IH} or V _{IL} V _O = V _{CC} or GND		5.5	—	±0.5	—	±5	—	±10	μA
Quiescent Supply Current, MSI I _{CC}	V _{CC} or GND	0	5.5	—	8	—	80	—	160	μA
Additional Quiescent Supply Current per Input Pin TTL Inputs High 1 Unit Load ΔI _{CC}	V _{CC} -2.1		4.5 to 5.5	—	2.4	—	2.8	—	3	mA

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#Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.

*Test verifies a minimum 50-ohm transmission-line-drive capability at +85°C, 75 ohms at +125°C.

ACT INPUT LOADING TABLES

CD54/74ACT240	
INPUT	UNIT LOADS*
nA0 - A3	1.42
10E	0.83
20E	0.83

CD54/74ACT241	
INPUT	UNIT LOADS*
nA0 - A3	0.5
10E	0.83
20E	1.67

CD54/74ACT244	
INPUT	UNIT LOADS*
nA0 - A3	0.5
10E	0.83
20E	0.83

*Unit load is ΔI_{CC} limit specified in Static Characteristics Chart, e.g., 2.4 mA max. @ 25°C.

CD54/74AC240/241/244

CD54/74ACT240/241/244

SWITCHING CHARACTERISTICS: AC Series; $t_r, t_f = 3 \text{ ns}$, $C_L = 50 \text{ pF}$

CHARACTERISTICS	SYMBOL	V _{CC} (V)	AMBIENT TEMPERATURE (T _A) - °C				UNITS
			-40 to +85		-55 to +125		
			MIN.	MAX.	MIN.	MAX.	
Propagation Delays: Data to Outputs AC240	t _{PLH} t _{PHL}	1.5 3.3* 5†	— 2.6 1.9	82 9.2 6.5	— 2.5 1.8	90 10.1 7.2	ns
AC241, 244	t _{PLH} t _{PHL}	1.5 3.3 5	— 3 2.2	93 10.5 7.5	— 2.9 2.1	103 11.5 8.2	ns
Output Enable Times	t _{PZL} t _{PZH}	1.5 3.3 5	— 4.6 3.1	136 16.4 10.9	— 4.5 3	150 18 12	ns
Output Disable Times	t _{PLZ} t _{PHZ}	1.5 3.3 5	— 3.9 3.1	136 13.6 10.9	— 3.8 3	150 15 12	ns
Power Dissipation Capacitance AC240 AC241, 244	C _{PD} §	— —	65 Typ. 71 Typ.		65 Typ. 71 Typ.		pF
Min. (Valley) V _{OH} During Switching of Other Outputs (Output Under Test Not Switching)	V _{OHV} See Fig. 1	5	4 Typ. @ 25°C				V
Max. (Peak) V _{OL} During Switching of Other Outputs (Output Under Test Not Switching)	V _{OLP} See Fig. 1	5	1 Typ. @ 25°C				V
Input Capacitance	C _i	—	—	10	—	10	pF
3-State Output Capacitance	C _o	—	—	15	—	15	pF

SWITCHING CHARACTERISTICS: ACT Series; $t_r, t_f = 3 \text{ ns}$, $C_L = 50 \text{ pF}$

CHARACTERISTICS	SYMBOL	V _{CC} (V)	AMBIENT TEMPERATURE (T _A) - °C				UNITS
			-40 to +85		-55 to +125		
			MIN.	MAX.	MIN.	MAX.	
Propagation Delays: Data to Outputs ACT240	t _{PLH} t _{PHL}	5†	2.3	7.8	2.2	8.6	ns
ACT241, 244	t _{PLH} t _{PHL}	5	2.5	8.7	2.4	9.6	ns
Output Enable Times	t _{PZL} t _{PZH}	5	3.5	12.2	3.4	13.4	ns
Output Disable Times	t _{PLZ} t _{PHZ}	5	3.5	12.2	3.4	13.4	ns
Power Dissipation Capacitance ACT240 ACT241, 244	C _{PD} §	— —	65 Typ. 71 Typ.		65 Typ. 71 Typ.		pF
Min. (Valley) V _{OH} During Switching of Other Outputs (Output Under Test Not Switching)	V _{OHV} See Fig. 1	5	4 Typ. @ 25°C				V
Max. (Peak) V _{OL} During Switching of Other Outputs (Output Under Test Not Switching)	V _{OLP} See Fig. 1	5	1 Typ. @ 25°C				V
Input Capacitance	C _i	—	—	10	—	10	pF
3-State Output Capacitance	C _o	—	—	15	—	15	pF

*3.3 V: min. is @ 3.6 V
max. is @ 3 V

†5 V: min. is @ 5.5 V
max. is @ 4.5 V

‡ C_{PD} is used to determine the dynamic power consumption, per package.

For AC series: $P_D = V_{CC}^2 f_i (C_{PD} + C_L)$

For ACT series: $P_D = V_{CC}^2 f_i (C_{PD} + C_L) + V_{CC} \Delta I_{CC}$ where f_i = input frequency

C_L = output load capacitance

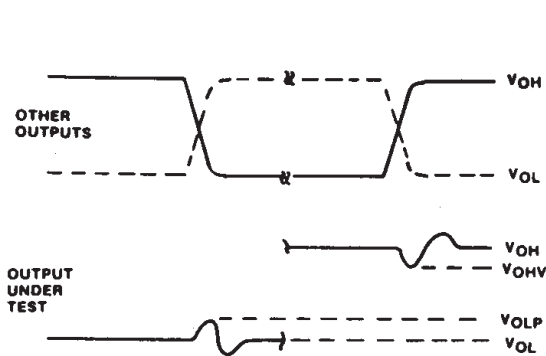
V_{CC} = supply voltage.

Technical Data

CD54/74AC240/241/244

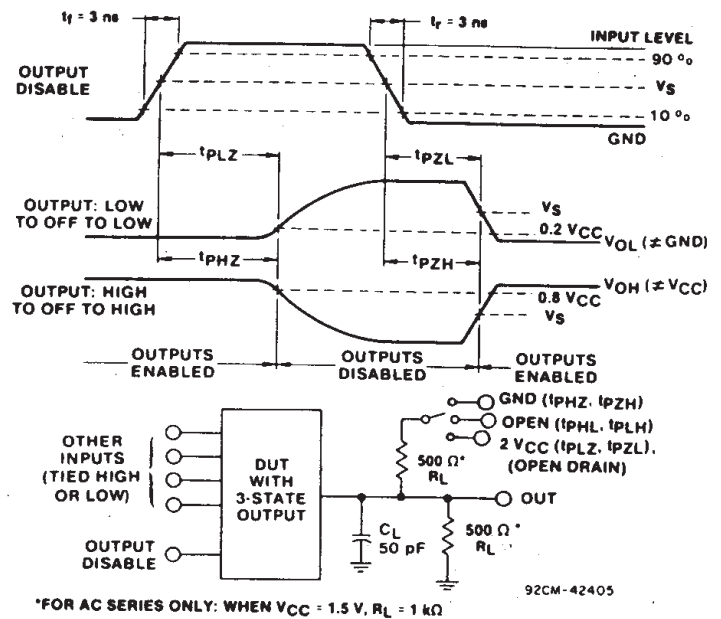
CD54/74ACT240/241/244

PARAMETER MEASUREMENT INFORMATION



- NOTES:
1. V_{OHV} AND V_{OLP} ARE MEASURED WITH RESPECT TO A GROUND REFERENCE NEAR THE OUTPUT UNDER TEST.
 2. INPUT PULSES HAVE THE FOLLOWING CHARACTERISTICS:
 $PRR \leq 1 \text{ MHz}$, $t_f = 3 \text{ ns}$, $t_r = 3 \text{ ns}$, SKEW 1 ns.
 3. R.F. FIXTURE WITH 700-MHz DESIGN RULES REQUIRED. IC SHOULD BE SOLDERED INTO TEST BOARD AND BYPASSED WITH $0.1 \mu\text{F}$ CAPACITOR. SCOPE AND PROBES REQUIRE 700-MHz BANDWIDTH.

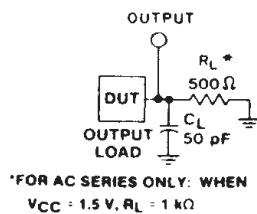
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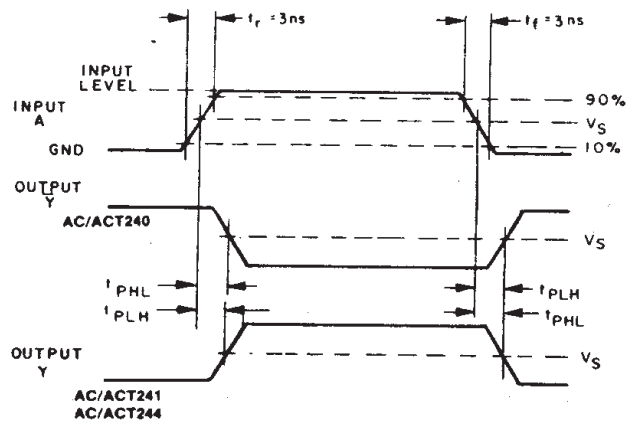
92CM-42405

Fig. 1 - Simultaneous switching transient waveforms.

Fig. 2 - Three-state propagation delay times and test circuit.



92CS-42389



92CS-42407

Fig. 3 - Propagation delay times and test circuit.

	CD54/74AC	CD54/74ACT
Input Level	V_{CC}	3 V
Input Switching Voltage, V_s	$0.5 V_{CC}$	1.5 V
Output Switching Voltage, V_s	$0.5 V_{CC}$	$0.5 V_{CC}$

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CD54AC240F3A	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD54AC240F3A	Samples
CD54AC244F3A	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD54AC244F3A	Samples
CD54ACT240F3A	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD54ACT240F3A	Samples
CD54ACT241F3A	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD54ACT241F3A	Samples
CD54ACT244F3A	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD54ACT244F3A	Samples
CD74AC240E	ACTIVE	PDIP	N	20	20	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74AC240E	Samples
CD74AC240EE4	ACTIVE	PDIP	N	20	20	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74AC240E	Samples
CD74AC240M	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC240M	Samples
CD74AC240M96	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC240M	Samples
CD74AC244E	ACTIVE	PDIP	N	20	20	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74AC244E	Samples
CD74AC244M	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC244M	Samples
CD74AC244M96	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC244M	Samples
CD74ACT240E	ACTIVE	PDIP	N	20	20	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74ACT240E	Samples
CD74ACT240M	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT240M	Samples
CD74ACT240M96	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT240M	Samples
CD74ACT240M96E4	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT240M	Samples
CD74ACT241E	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74ACT241E	Samples
CD74ACT241M96	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT241M	Samples
CD74ACT244E	ACTIVE	PDIP	N	20	20	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74ACT244E	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CD74ACT244M	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT244M	Samples
CD74ACT244M96	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT244M	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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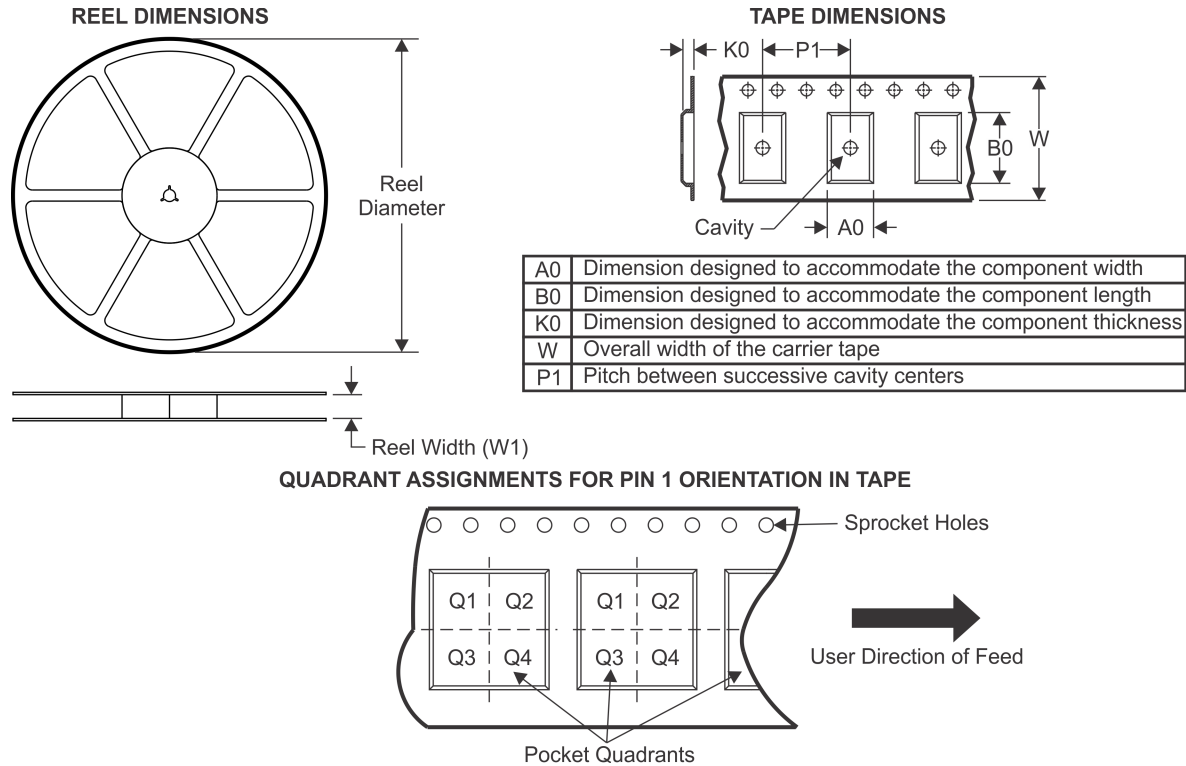
OTHER QUALIFIED VERSIONS OF CD54AC240, CD54AC244, CD54ACT240, CD54ACT241, CD54ACT244, CD74AC240, CD74AC244, CD74ACT240, CD74ACT241, CD74ACT244 :

- Catalog : [CD74AC240](#), [CD74AC244](#), [CD74ACT240](#), [CD74ACT241](#), [CD74ACT244](#)
- Military : [CD54AC240](#), [CD54AC244](#), [CD54ACT240](#), [CD54ACT241](#), [CD54ACT244](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

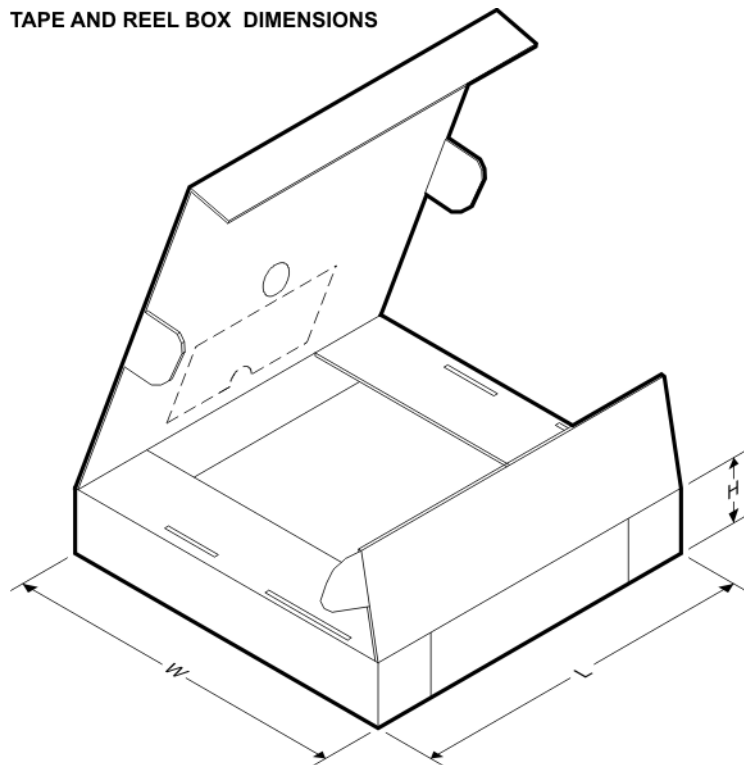
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74AC240M96	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
CD74AC244M96	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
CD74ACT240M96	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
CD74ACT241M96	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
CD74ACT244M96	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1

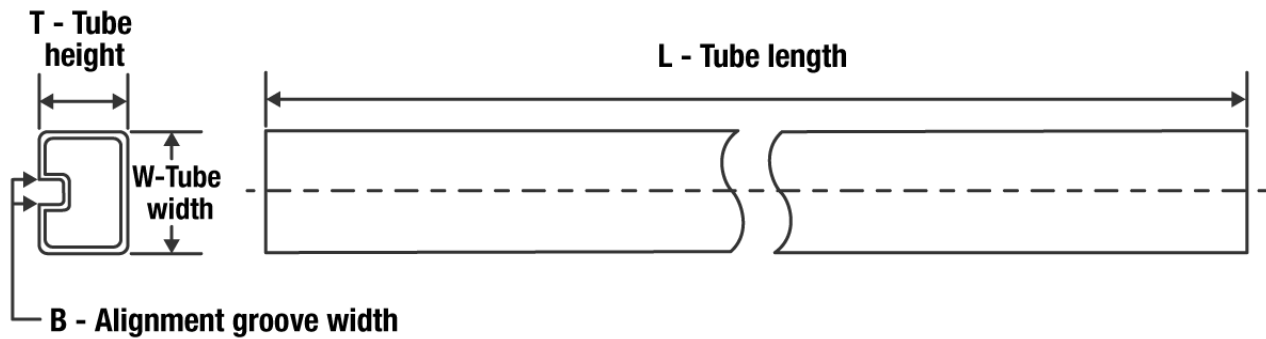
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74AC240M96	SOIC	DW	20	2000	367.0	367.0	45.0
CD74AC244M96	SOIC	DW	20	2000	367.0	367.0	45.0
CD74ACT240M96	SOIC	DW	20	2000	367.0	367.0	45.0
CD74ACT241M96	SOIC	DW	20	2000	367.0	367.0	45.0
CD74ACT244M96	SOIC	DW	20	2000	367.0	367.0	45.0

TUBE



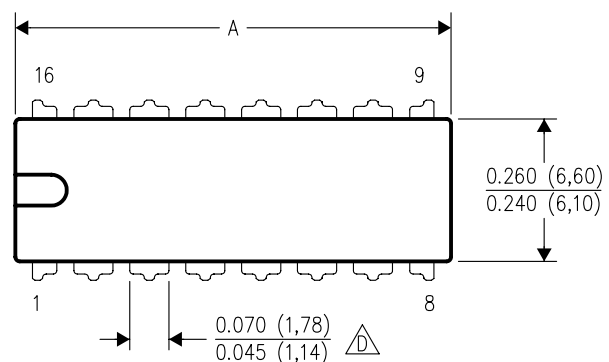
*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
CD74AC240E	N	PDIP	20	20	506	13.97	11230	4.32
CD74AC240EE4	N	PDIP	20	20	506	13.97	11230	4.32
CD74AC240M	DW	SOIC	20	25	507	12.83	5080	6.6
CD74AC244E	N	PDIP	20	20	506	13.97	11230	4.32
CD74AC244M	DW	SOIC	20	25	507	12.83	5080	6.6
CD74ACT240E	N	PDIP	20	20	506	13.97	11230	4.32
CD74ACT240M	DW	SOIC	20	25	507	12.83	5080	6.6
CD74ACT241E	N	PDIP	20	20	506	13.97	11230	4.32
CD74ACT244E	N	PDIP	20	20	506	13.97	11230	4.32
CD74ACT244M	DW	SOIC	20	25	507	12.83	5080	6.6

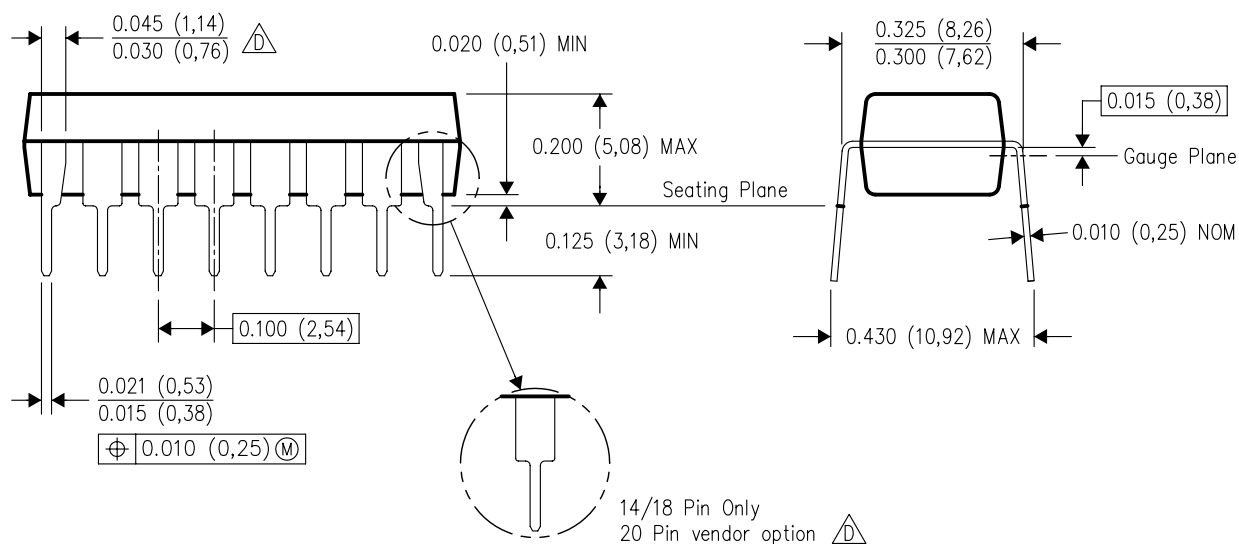
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE

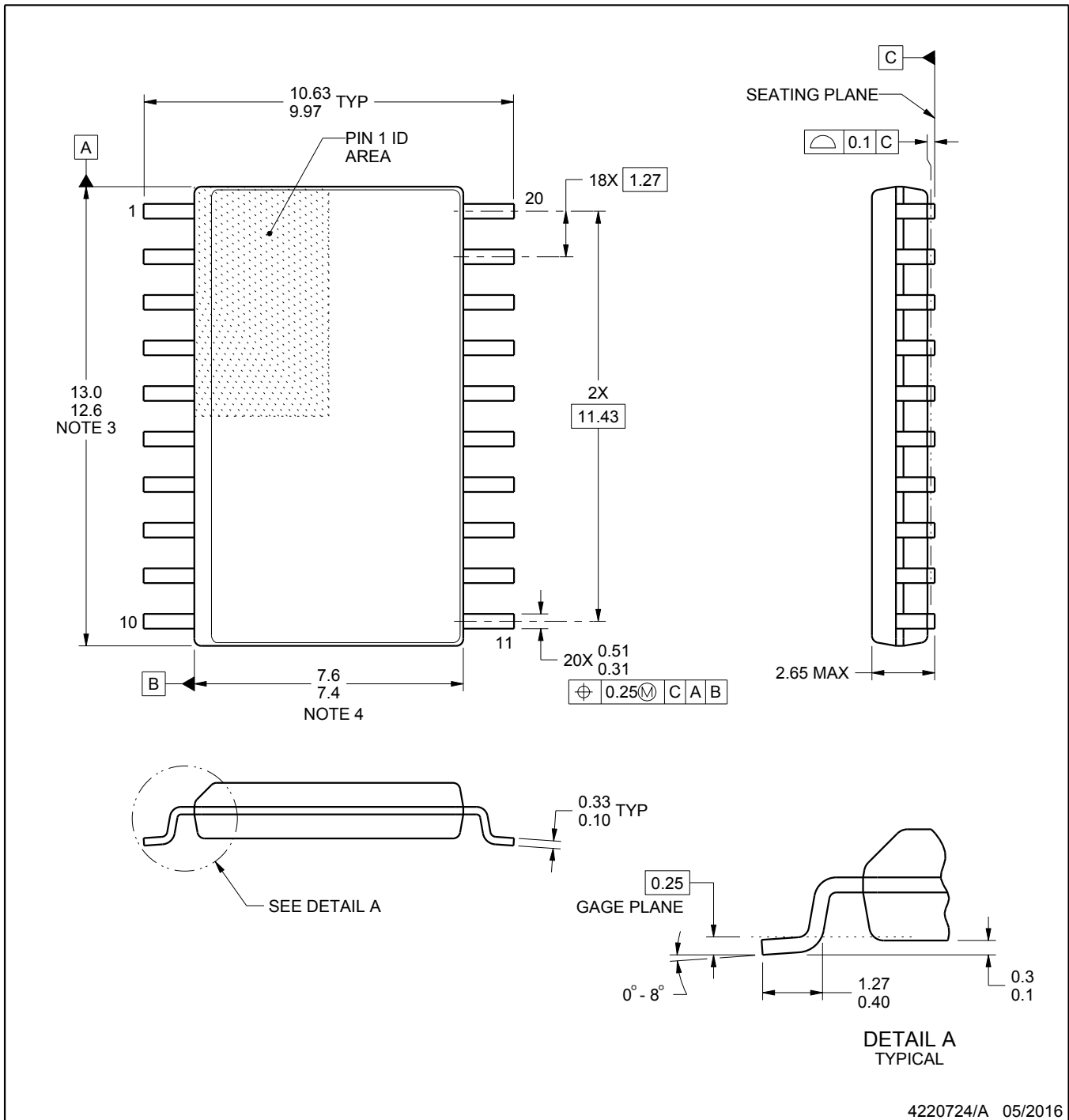
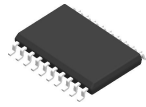


PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 -  The 20 pin end lead shoulder width is a vendor option, either half or full width.



NOTES:

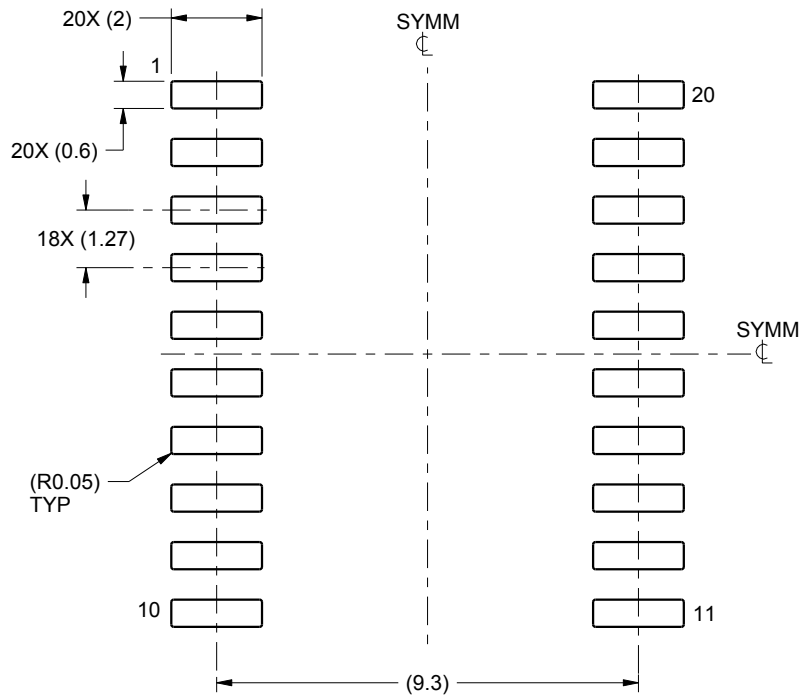
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

EXAMPLE BOARD LAYOUT

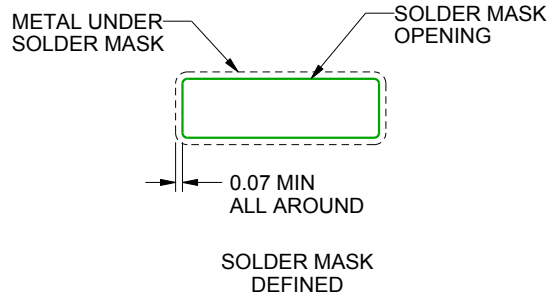
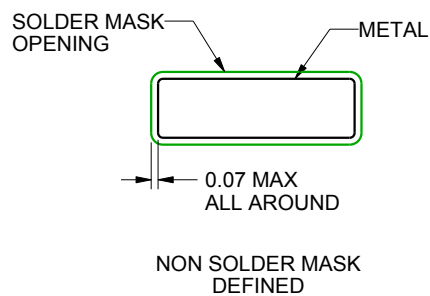
DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

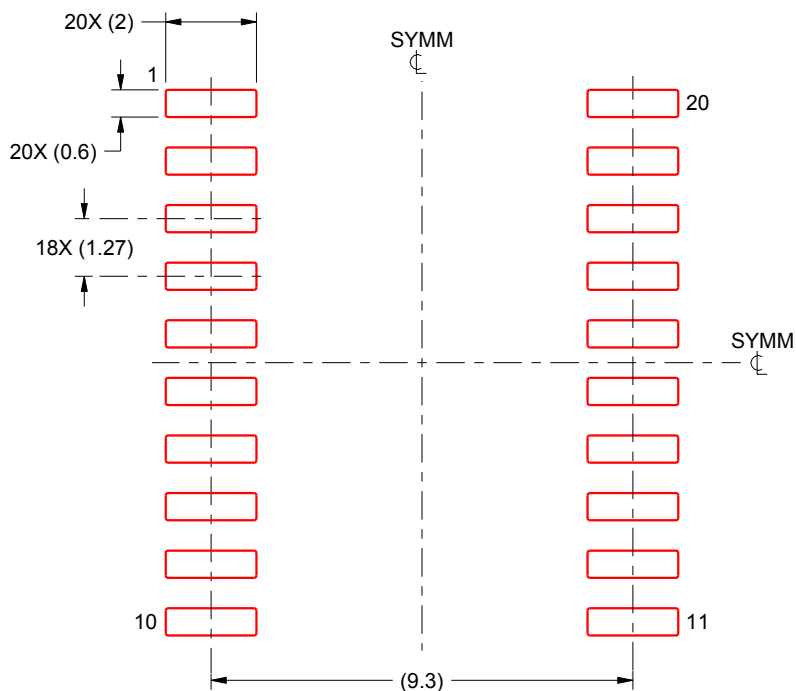
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

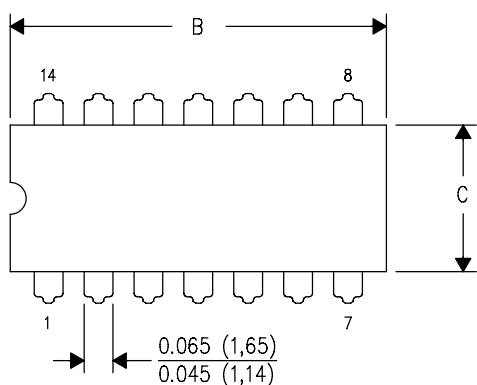
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

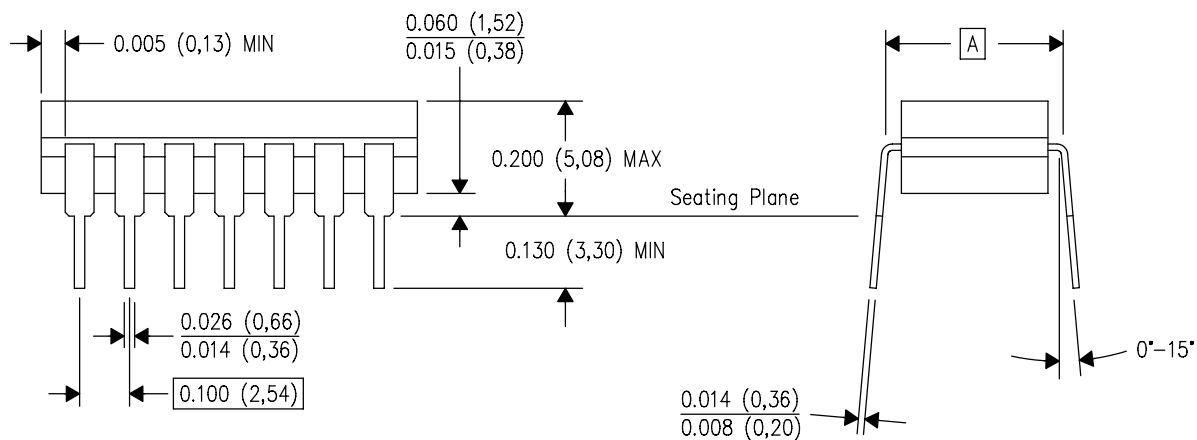
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

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